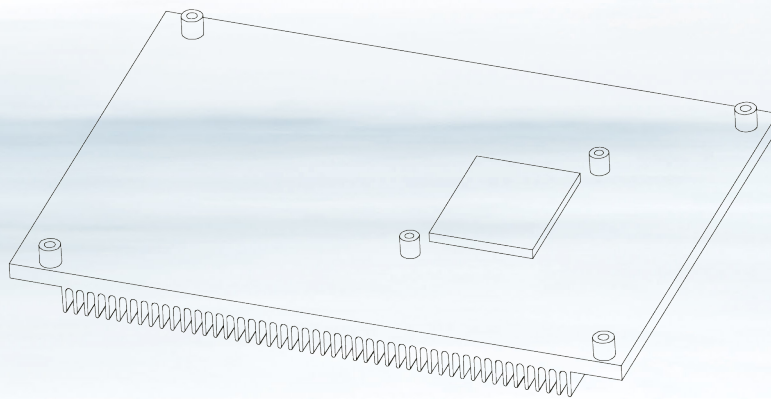


HEATSINK KIT

1067-5540



Heatsink Kit for 3.5"-SBC-APL E-Series Single Board Computer

- ▶ Aluminum heatsink
- ▶ Screw-in type mounting
- ▶ Max. 12 W TDP

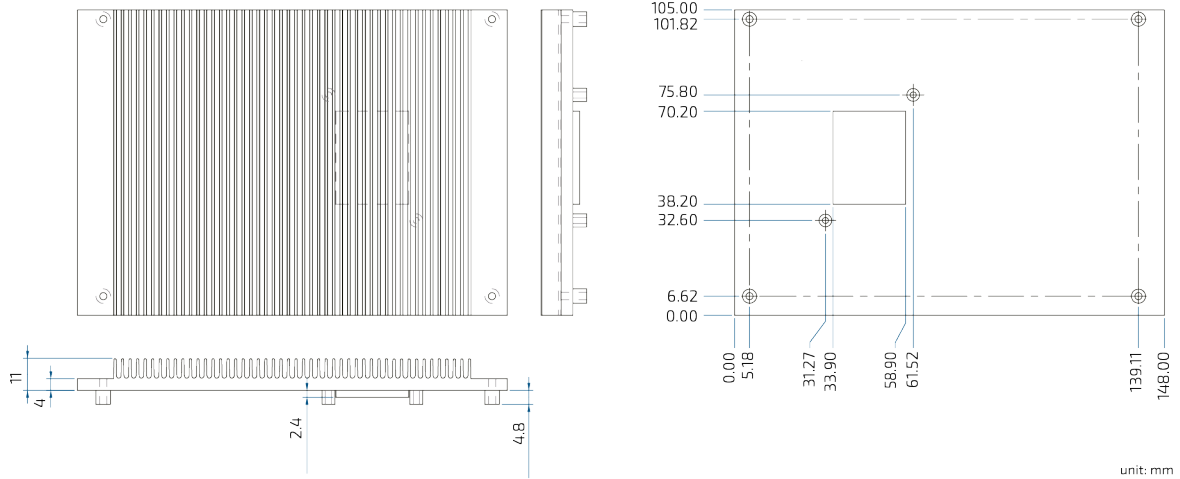
POSSIBILITIES START HERE

TECHNICAL INFORMATION

MECHANICAL CHARACTERISTICS	SINK DIMENSION (W X D X H)	148.0 mm x 105.0 mm x 15.8 mm (5.83" x 4.13" x 0.62")
APPLICATION	SUPPORTED MAINBOARDS MAXIMUM CPU TDP SUPPORT	3.5"-SBC-APL V2.0 E-Series 12 W*

*It depends on the overall system design and airflow pattern inside the case

MECHANICAL DIMENSIONS



ORDERING INFORMATION

ARTICLE	PART NO.	DESCRIPTION
HEATSINK KIT	1067-5540	Heatsink w/ thermal pad, 4x M3x5, 2x M2.5x4 screw for 3.5"-SBC-APL w/ 12 W CPU

GLOBAL HEADQUARTERS

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